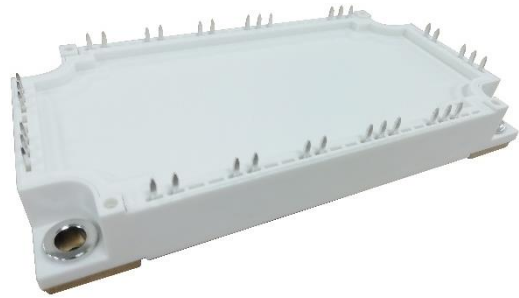


1200V/75A PIM

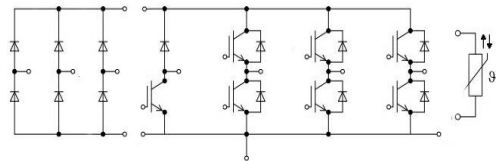
Features:

- 1200V75A, $V_{CE(sat)}(typ.)=2.10V$
- Lower losses and higher energy
- Excellent short circuit ruggedness
- 62mm PIM module



General Applications:

Daxin's IGBTs offer lower losses and higher energy for application such as motor drive ,inverter and other soft switching applications.



Equivalent Circuit Schematic

IGBT, Inverter

Maximum Ratings of IGBT

V_{CES}	Collector to Emitter Voltage		1200	V
V_{GES}	Continuous Gate to Emitter Voltage		± 30	V
I_C	Continuous Collector Current	$T_C = 25^\circ C$	150	A
		$T_C = 100^\circ C$	75	
I_{CM}	Pulse Collector Current	$T_J = 150^\circ C$	150	A
P_D	Maximum Power Dissipation (IGBT)	$T_C = 25^\circ C,$ $T_J = 150^\circ C$	510	W
t_{sc}	Short Circuit Withstand Time		> 10	μs
T_J	Maximum IGBT Junction Temperature		150	$^\circ C$
T_{JOP}	Maximum Operating Junction Temperature Range		-40 to +150	$^\circ C$
T_{stg}	Storage Temperature Range		-40 to +125	$^\circ C$

Absolute Maximum Ratings of Freewheeling Diode

V_{RRM}	Repetitive Peak Reverse Voltage Preliminary Data		1200	V
I_F	Diode Continuous Forward Current	$T_C = 25^\circ C$	150	A
	Diode Continuous Forward Current	$T_C = 100^\circ C$	75	
I_{FM}	Diode Maximum Forward Current		150	A

Electrical Characteristics of IGBT at $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter	Test Conditions	Min	Typ	Max	Unit
BV_{CES}	Collector to Emitter Breakdown Voltage $V_{GE} = 0V, I_C = 1mA$	1200			V
I_{CES}	Collector to Emitter Leakage Current $V_{GE} = 0V, V_{CE} = V_{CES}$			1	mA
I_{GES}	Gate to Emitter Leakage Current $V_{GE} = \pm 30V, V_{CE} = 0V$			200	nA
$V_{GE(th)}$	Gate Threshold Voltage $I_C = 1mA, V_{CE} = V_{GE}$	4.5		5.7	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage (Module Level) $I_C = 75A, V_{GE} = 15V$	$T_J = 25^\circ\text{C}$	2.10	2.30	V
		$T_J = 125^\circ\text{C}$	2.50		

Switching Characteristics of IGBT

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600V$ $I_C = 75A$ $R_G = 10\Omega$ $V_{GE} = \pm 15V$ Inductive Load	$T_J = 25^{\circ}C$		25		ns
			$T_J = 125^{\circ}C$		30		
t_r	Turn-on Rise Time		$T_J = 25^{\circ}C$		40		ns
			$T_J = 125^{\circ}C$		45		
$t_{d(off)}$	Turn-off Delay Time		$T_J = 25^{\circ}C$		320		ns
			$T_J = 125^{\circ}C$		350		
t_f	Turn-off Fall Time		$T_J = 25^{\circ}C$		160		ns
			$T_J = 125^{\circ}C$		180		
E_{on}	Turn-on Switching Loss		$T_J = 25^{\circ}C$		5.5		mJ
			$T_J = 125^{\circ}C$		7.5		
E_{off}	Turn-off Switching Loss		$T_J = 25^{\circ}C$		5.1		mJ
			$T_J = 125^{\circ}C$		8.5		
Q_g	Total Gate Charge		$T_J = 25^{\circ}C$		680		nC
R_{gint}	Integrated gate resistor	$f = 1M;$ $V_{pp} = 1V$	$T_J = 25^{\circ}C$		2.5		Ω
C_{ies}	Input Capacitance	$V_{CE} = 25V$ $V_{GE} = 0V$ $f = 1MHz$	$T_J = 25^{\circ}C$		5.9		nF
C_{oes}	Output Capacitance		$T_J = 25^{\circ}C$		0.92		
C_{res}	Reverse Transfer Capacitance		$T_J = 25^{\circ}C$		0.53		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (IGBT)					0.245	$^{\circ}C/W$

Electrical and Switching Characteristics of Freewheeling Diode

V _F	Diode Forward Voltage	I _F = 75A , V _{GE} = 0V	T _J = 25°C		1.90	2.20	V
			T _J = 125°C		1.90		
t _{rr}	Diode Reverse Recovery Time	I _F = 75A, di/dt = 1200A/μs, V _{rr} = 600V,	T _J = 25°C		150		ns
			T _J = 125°C		270		
I _{rr}	Diode Peak Reverse Recovery Current		T _J = 25°C		90		A
			T _J = 125°C		100		
Q _{rr}	Diode Reverse Recovery Charge		T _J = 25°C		7.00		uC
			T _J = 125°C		11.50		
E _{rr}	Diode Reverse Recovery Energy		T _J = 25°C		2.30		mJ
			T _J = 125°C		4.30		
R _{θJC}	Thermal Resistance, Junction-to-Case (Diode)					0.63	°C/W

Diode, Rectifier Maximum Rated Values

V_{RRM}	Repetitive Peak Reverse Voltage	$T_J = 25^\circ C$	1800	V
I_{FRMSM}	Maximum RMS forward current per chip	$T_C = 80^\circ C$	75	A
I_{RMSM}	Maximum RMS current at rectifier output	$T_C = 80^\circ C$	150	
I_{FSM}	Surge Current @ $t_p=10$ ms	$T_J = 25^\circ C$	840	A
I^2t	I^2t - value	$T_J = 25^\circ C$	3528	A^2s

Electrical Characteristics of Diode

V _F	Diode Forward Voltage	I _F = 75A	T _J = 25°C		1.05		V
			T _J = 125°C		0.85		
I _R	Reverse current		T _J = 125°C		1.0		mA
R _{θJC}	Thermal Resistance, Junction-to-Case (Diode)					0.65	°C/W

IGBT, Brake-Chopper Maximum Ratings of IGBT

V_{CES}	Collector to Emitter Voltage		1200	V
V_{GES}	Continuous Gate to Emitter Voltage		± 30	V
I_C	Continuous Collector Current	$T_C = 25^\circ\text{C}$	100	A
		$T_C = 100^\circ\text{C}$	50	
I_{CM}	Pulse Collector Current	$T_J = 150^\circ\text{C}$	100	A
P_D	Maximum Power Dissipation (IGBT)	$T_C = 25^\circ\text{C}$, $T_J = 150^\circ\text{C}$	365	W
t_{sc}	Short Circuit Withstand Time		> 10	μs
T_J	Maximum IGBT Junction Temperature		150	$^\circ\text{C}$
T_{JOP}	Maximum Operating Junction Temperature Range		-40 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range		-40 to +125	$^\circ\text{C}$

Electrical Characteristics of IGBT at $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter		Test Conditions	Min	Typ	Max	Unit
BV_{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0\text{V}$, $I_C = 1\text{mA}$	1200			V
I_{CES}	Collector to Emitter Leakage Current	$V_{GE} = 0\text{V}$, $V_{CE} = V_{CES}$			1	mA
I_{GES}	Gate to Emitter Leakage Current	$V_{GE} = \pm 30\text{V}$, $V_{CE} = 0\text{V}$			200	nA
$V_{GE(th)}$	Gate Threshold Voltage	$I_C = 1\text{mA}$, $V_{CE} = V_{GE}$	4.5		5.7	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage (Module Level)	$I_C = 50\text{A}$, $V_{GE} = 15\text{V}$	$T_J = 25^\circ\text{C}$	2.10	2.30	V
			$T_J = 125^\circ\text{C}$	2.50		

Switching Characteristics of IGBT

Switching Characteristics of IGBT							
$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600V$ $I_C = 50A$ $R_G = 13\Omega$ $V_{GE} = \pm 15V$ Inductive Load	$T_J = 25^{\circ}C$		20		ns
			$T_J = 125^{\circ}C$		25		
t_r	Turn-on Rise Time		$T_J = 25^{\circ}C$		40		ns
			$T_J = 125^{\circ}C$		45		
$t_{d(off)}$	Turn-off Delay Time		$T_J = 25^{\circ}C$		300		ns
			$T_J = 125^{\circ}C$		330		
t_f	Turn-off Fall Time		$T_J = 25^{\circ}C$		160		ns
			$T_J = 125^{\circ}C$		180		

E _{on}	Turn-on Switching Loss	V _{CC} = 600V I _C = 50A R _G = 13Ω V _{GE} = ±15V Inductive Load	T _J = 25°C		4.50		mJ
			T _J = 125°C		6.50		
E _{off}	Turn-off Switching Loss		T _J = 25°C		4.20		mJ
			T _J = 125°C		6.10		
Q _g	Total Gate Charge		T _J = 25°C		430		nC
R _{gint}	Integrated gate resistor	f = 1M; V _{pp} = 1V	T _J = 25°C		2.2		Ω
C _{ies}	Input Capacitance	V _{CE} = 25V V _{GE} = 0V f = 1MHz	T _J = 25°C		3.80		nF
C _{oes}	Output Capacitance		T _J = 25°C		0.51		
C _{res}	Reverse Transfer Capacitance		T _J = 25°C		0.33		
R _{θJC}	Thermal Resistance, Junction-to-Case (IGBT)					0.343	°C/W

Diode, Brake-Chopper Maximum Rated Values

V_{RRM}	Repetitive Peak Reverse Voltage Preliminary Data		1200	V
I_F	Diode Continuous Forward Current	$T_C = 25^\circ C$	100	A
		$T_C = 100^\circ C$	50	
I_{FM}	Diode Maximum Forward Current		100	A

Electrical and Switching Characteristics of Freewheeling Diode

V _F	Diode Forward Voltage	I _F = 50A , V _{GE} = 0V	T _J = 25°C		1.90	2.20	V
			T _J = 125°C		1.90		
t _{rr}	Diode Reverse Recovery Time	I _F = 50A, di/dt = 1200A/μs, V _{rr} = 600V,	T _J = 25°C		110		ns
			T _J = 125°C		250		
I _{rr}	Diode Peak Reverse Recovery Current		T _J = 25°C		85		A
			T _J = 125°C		100		
Q _{rr}	Diode Reverse Recovery Charge		T _J = 25°C		5.5		uC
			T _J = 125°C		9.50		
E _{rr}	Diode Reverse Recovery Energy		T _J = 25°C		1.80		mJ
			T _J = 125°C		3.70		
R _{θJC}	Thermal Resistance, Junction-to-Case (Diode)					0.652	°C/W

NTC - Thermistor Characteristic Values

R ₂₅	T _C = 25°C	5		KΩ
ΔR/R	T _C = 100°C, R ₁₀₀ =493Ω		±5	%
P ₂₅	T _C = 25°C	50		mW
B _{25/50}	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15K))]$	3375		K
B _{25/80}	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15K))]$	3410		K

Module Characteristics

Parameter		Min.	Typ.	Max.	Unit
V _{iso}	Isolation Voltage (All Terminals Shorted), f = 50Hz, 1minute			2500	V
R _{θCS}	Case-To-Sink(Conductive Grease Applied)		0.1		°C/W
M	Mounting Screw: M5	3.0		6.0	N·m
G	Weight		300		g

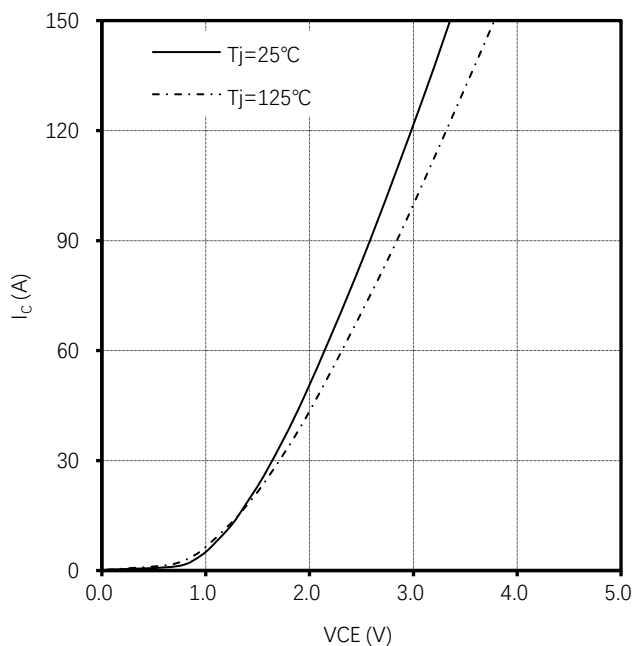


Fig 1. Output characteristic IGBT,
 $I_c=f(V_{ce}), V_{GE}=15V$

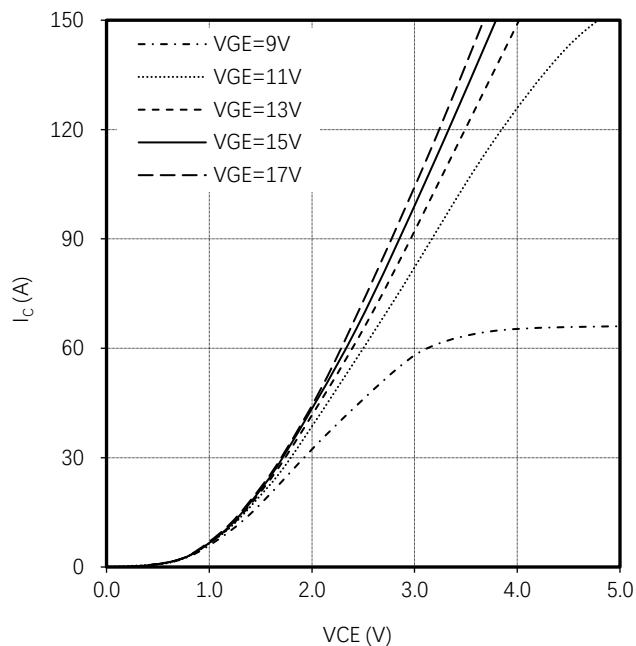


Fig 2. Output characteristic IGBT,
 $I_c=f(V_{ce}), T_j=125^\circ C$

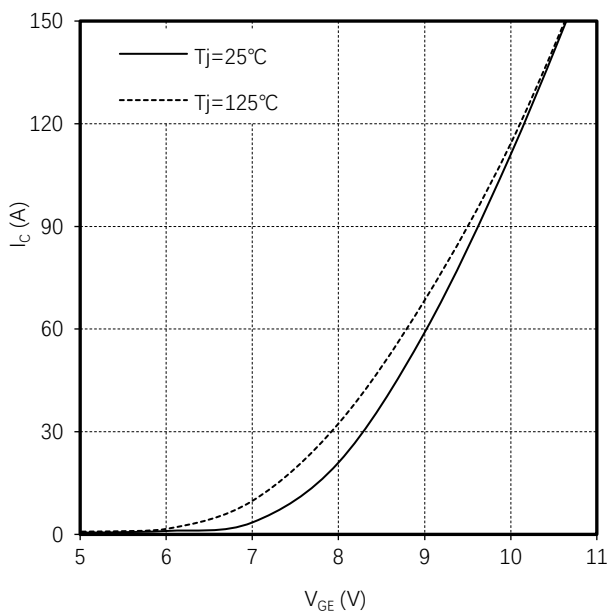


Fig 3. Transfer characteristic IGBT
 $I_c=f(V_{GE}), V_{CE}=20V$

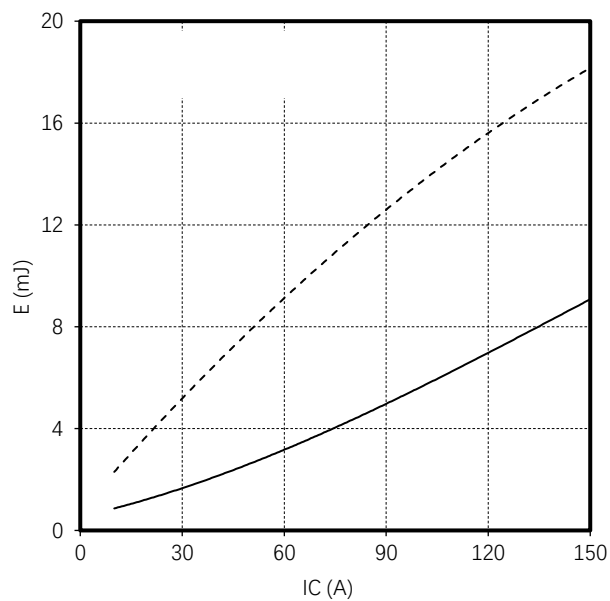


Fig 4. Switching losses IGBT, $E_{on}=f(I_c), E_{off}=f(I_c)$,
 $V_{GE}=\pm 15V, R_{Gon}=4.7\Omega, R_{Goff}=4.7\Omega, V_{CE}=600V$

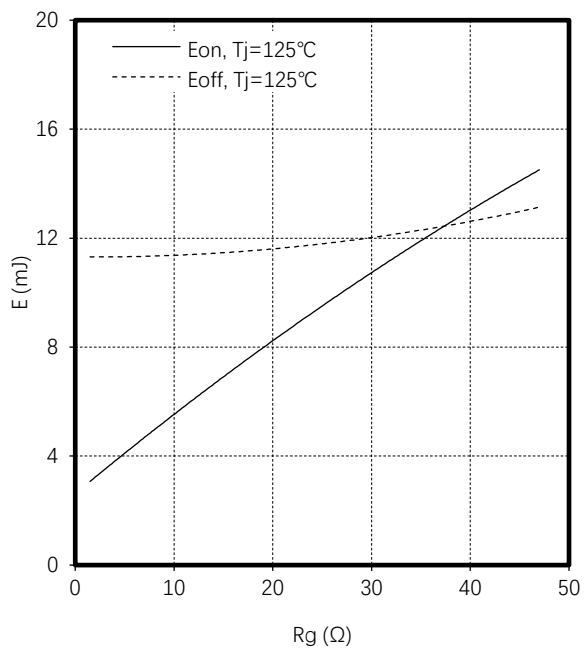


Fig 5. Switching losses IGBT, $E_{on}=f(R_G)$, $E_{off}=f(R_G)$,
 $V_{GE}=\pm 15V$, $I_C=75A$, $V_{CE}=600V$

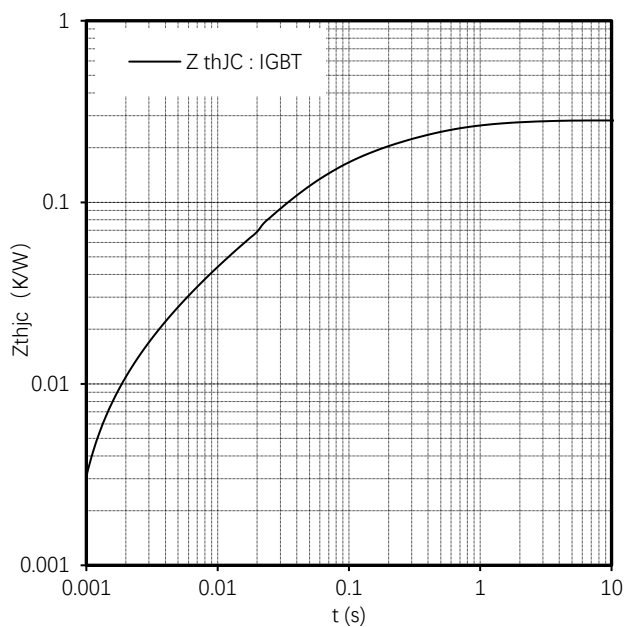


Fig 6. Transient thermal impedance IGBT , $Z_{thjc}=f(t)$

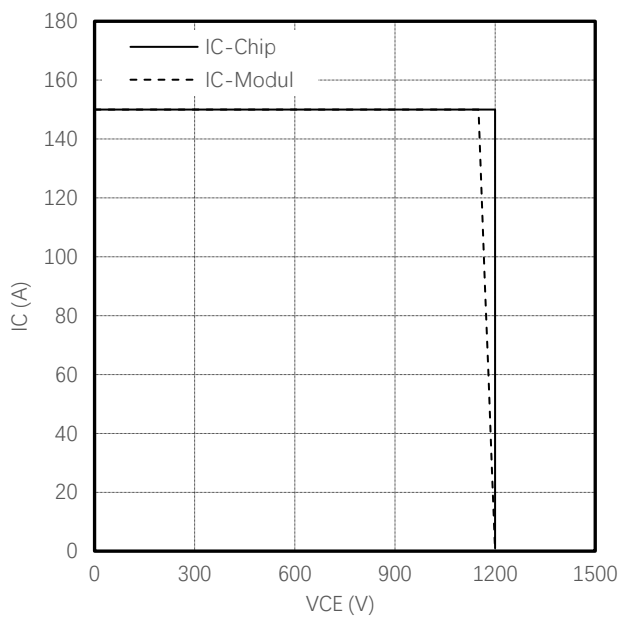


Fig 7. Reverse bias safe operating area IGBT,
 $I_C=f(V_{CE})$, $V_{GE}=\pm 15V$, $R_{Goff}=4.7\Omega$, $T_j=125^\circ C$

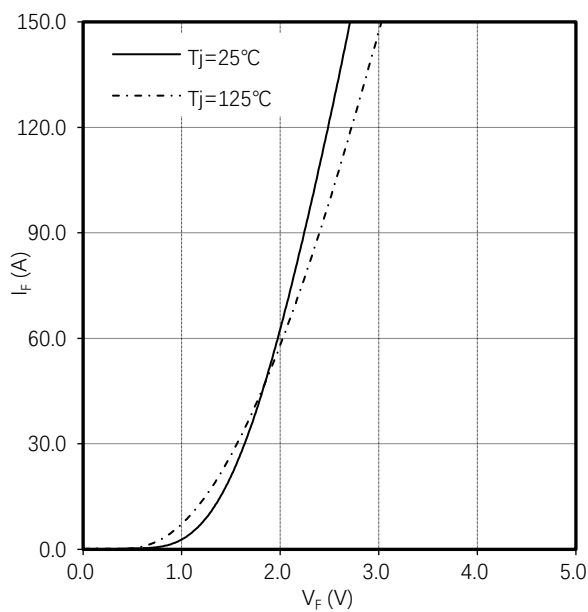


Fig 8. Forward characteristic of Diode ,
 $I_F=f(V_F)$

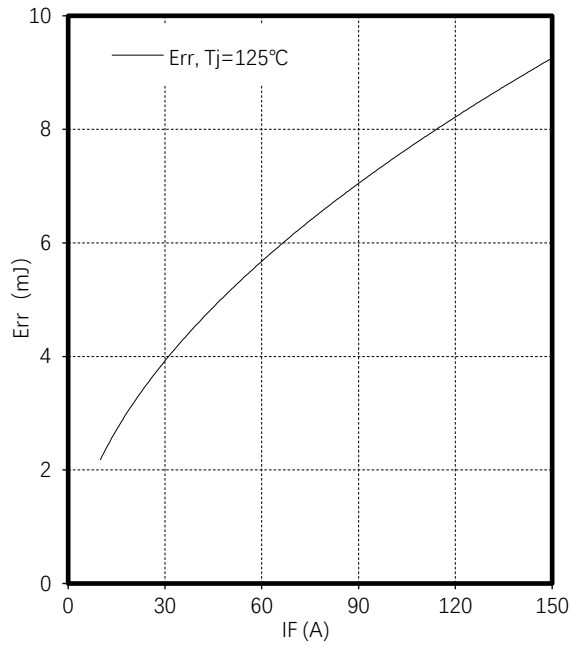


Fig 9. Switching losses Diode,
 $E_{rr}=f(I_F)$, $R_{Gon}=4.7\Omega$, $V_{CE}=600V$

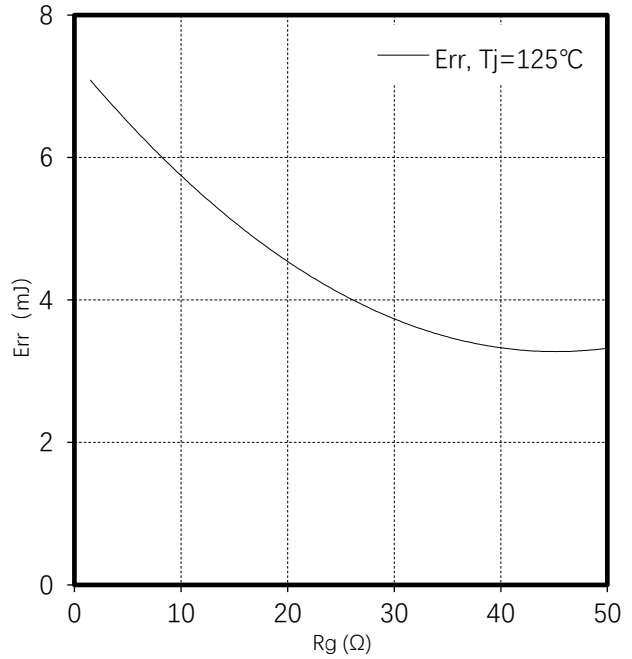


Fig 10. Switching losses Diode,
 $E_{rr}=f(R_G)$, $I_F=75A$, $V_{CE}=600V$

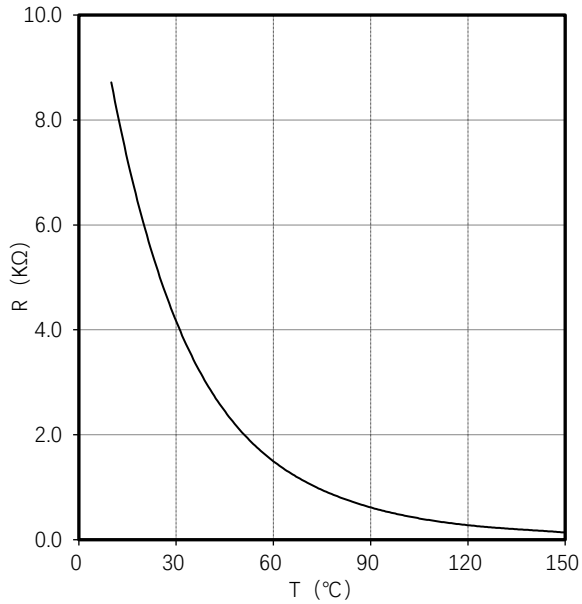
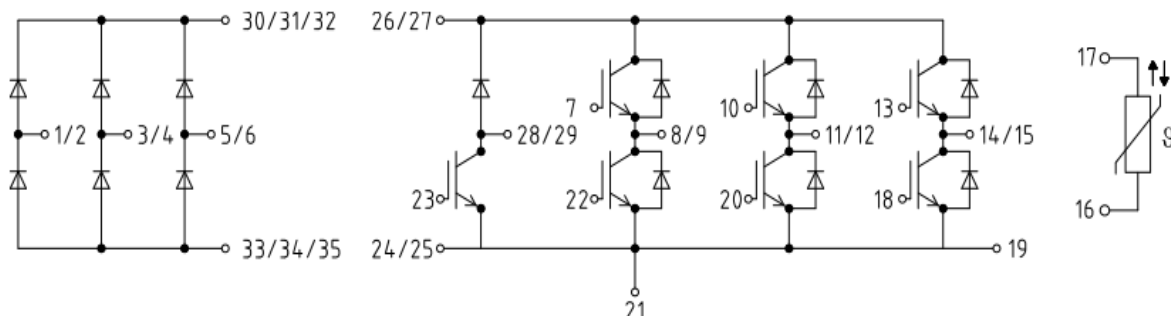


Fig 11. NTC-Thermistor-temperature
characteristic (typical)

Internal Circuit:



Package Dimension
Dimensions in Millimeters

